- Compatible With IEEE Std 1194.1-1991 (BTL)
- TTL A Port, Backplane Transceiver Logic (BTL) B Port
- Open-Collector B-Port Outputs Sink 100 mA
- BIAS V<sub>CC</sub> Minimizes Signal Distortion During Live Insertion or Withdrawal

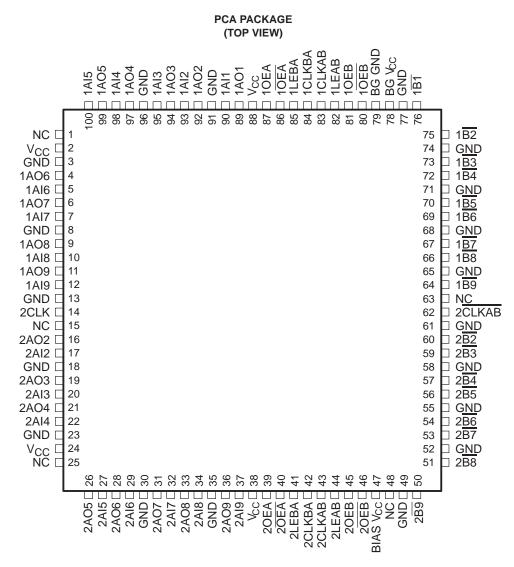
 High-Impedance State During Power Up and Power Down

WITH BUFFERED CLOCK LINE SCBS1770 – OCTOBER 1993 – REVISED MARCH 2004

**17-BIT TTL/BTL UNIVERSAL STORAGE TRANSCEIVER** 

SN74FB1651

- B-Port Biasing Network Preconditions the Connector and PC Trace to the BTL High-Level Voltage
- TTL-Input Structures Incorporate Active Clamping to Aid in Line Termination



NC - No internal connection



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#### description/ordering information

The SN74FB1651 contains an 8-bit and 9-bit transceiver with a buffered clock. The clock and the transceivers are designed to translate signals between TTL and backplane transceiver-logic (BTL) environments. The device is designed specifically to be compatible with IEEE Std 1194.1-1991.

The B port operates at BTL-signal levels. The open-collector B ports are specified to sink 100 mA. Two output enables (OEB and  $\overline{OEB}$ ) are provided for the  $\overline{B}$  outputs. When OEB is low,  $\overline{OEB}$  is high, or V<sub>CC</sub> is less than 2.1 V, the  $\overline{B}$  port is turned off.

The A port operates at TTL-signal levels. The A outputs reflect the inverse of the data at the B port when the A-port output enable (OEA) is high. When OEA is low or when V<sub>CC</sub> is less than 2.1 V, the A outputs are in the high-impedance state.

BIAS  $V_{CC}$  establishes a voltage between 1.62 V and 2.1 V on the BTL outputs when  $V_{CC}$  is not connected.

BG  $V_{\mbox{CC}}$  and BG GND are the supply inputs for the bias generator.

#### **ORDERING INFORMATION**

TA	PACKAGET		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
0°C to 70°C	TQFP – PCA	Tube	SN74FB1651PCA	FB1651	

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

#### **Function Tables**

#### TRANSCEIVER

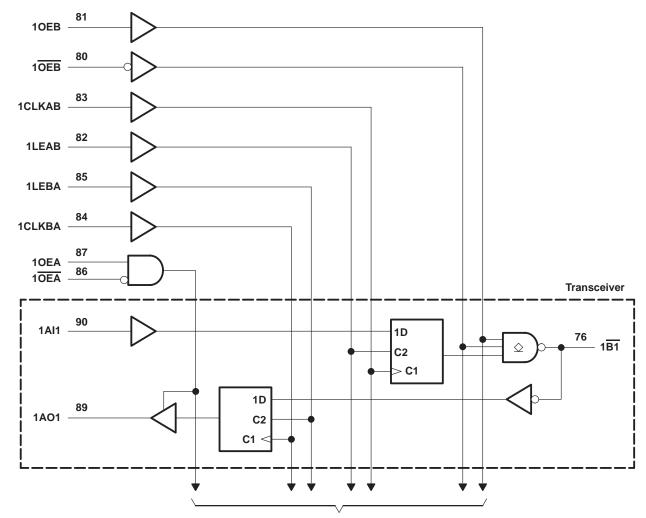
	INP	UTS		FUNCTION		
OEA	OEA	OEB	OEB	FUNCTION		
Х	Х	Н	L	A data to B bus		
L	н	Х	Х	B data to A bus		
L	Н	Н	L	$\overline{A}$ data to B bus, $\overline{B}$ data to A bus		
Х	Х	L	Х			
Х	Х	Х	н	B-bus isolation		
Н	Х	Х	Х	A hus indiction		
Х	L	Х	Х	A-bus isolation		

#### STORAGE MODE

INP	UTS	FUNCTION			
LE	CLK	FUNCTION			
Н	Х	Transparent			
L	$\uparrow$	Store data			
L	L	Storage			



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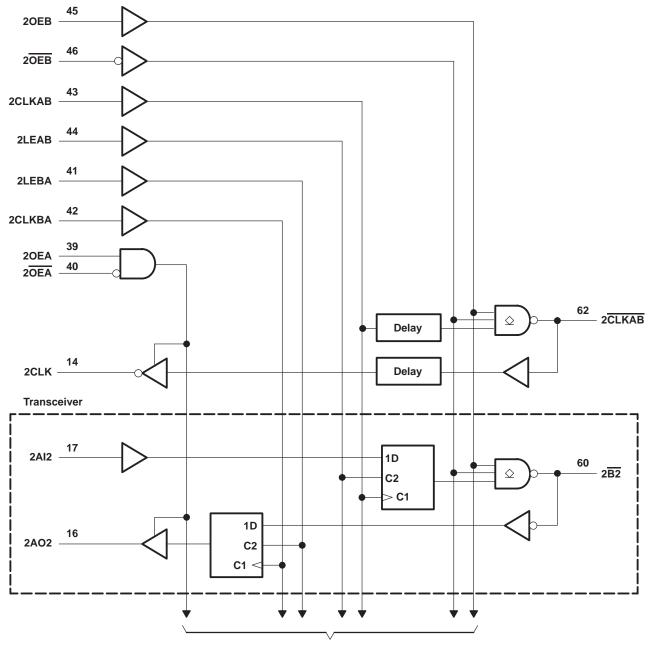
functional block diagram

**To Eight Other Channels** 



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### functional block diagram (continued)



**To Seven Other Channels** 



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#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub> , BIAS V <sub>CC</sub> , BG V <sub>CC</sub> Input voltage range, V <sub>I</sub> : Except B port B port Voltage range applied to any B output in the disabled or power-off state, V <sub>O</sub> Voltage range applied to any output in the high state, V <sub>O</sub> Input clamp current, I <sub>IK</sub> : Except B port B port Current applied to any single output in the low state, I <sub>O</sub> : A port	$\begin{array}{cccc} & -1.2 \ V \ to \ 7 \ V \\ & -1.2 \ V \ to \ 3.5 \ V \\ & -0.5 \ V \ to \ 3.5 \ V \\ & -0.5 \ V \ to \ V_{CC} \\ & -40 \ mA \\ & -18 \ mA \end{array}$
Package thermal impedance, θ <sub>JA</sub> (see Note 1)	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

#### recommended operating conditions (see Note 2)

			MIN	NOM	MAX	UNIT
V <sub>CC,</sub> BG V <sub>CC</sub> , BIAS V <sub>CC</sub>	Supply voltage		4.5	5	5.5	V
		B port	1.62		2.3	
VIH	High-level input voltage	Except B port	2			V
		B port	0.75		1.47	
VIL	Low-level input voltage	Except B port			0.8	V
IK	Input clamp current				-18	mA
IOH	High-level output current	A port			-3	mA
		A port			24	
IOL	Low-level output current	B port			100	mA
Т <sub>А</sub>	Operating free-air temperature	·	0		70	°C

NOTE 2: To ensure proper device operation, all unused inputs must be terminated as follows: A and control inputs to V<sub>CC</sub>(5 V) or GND, and B inputs to GND only. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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#### electrical characteristics over recommended operating free-air temperature range

PARAMETER		TEST CONDITIONS			TYP†	MAX	UNIT
	B port	V <sub>CC</sub> = 4.5 V,	lj = -18 mA			-1.2	
VIK	Except B port	V <sub>CC</sub> = 4.5 V,	II = -40 mA			-0.5	V
VOH	AO port	V <sub>CC</sub> = 4.5 V,	IOH = -3 mA	2.5	3.3		V
	AO port	V <sub>CC</sub> = 4.5 V,	I <sub>OL</sub> = 24 mA		0.35	0.5	
VOL			I <sub>OL</sub> = 80 mA	0.75		1.1	V
	B port	$V_{CC} = 4.5 V$	I <sub>OL</sub> = 100 mA			1.15	
lj	Except B port	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 5.5 V			50	μA
чн‡	Except B port	V <sub>CC</sub> = 5.5 V,	VI = 2.7 V			50	μΑ
. +	Except B port	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 0.5 V			-50	
'⊪_‡	B port	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 0.75 V			-100	μA
IOZH	AO port	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.7 V			50	μΑ
IOZL	AO port	V <sub>CC</sub> = 5.5 V,	$V_{O} = 0.5 V$			-50	μΑ
IOZPU	AO port	$V_{CC} = 0$ to 2.1 V,	$V_{O}$ = 0.5 V to 2.7 V			50	μΑ
IOZPD	AO port	V <sub>CC</sub> = 2.1 V to 0,	$V_{O}$ = 0.5 V to 2.7 V			-50	μΑ
IОН	B port	$V_{CC} = 0$ to 5.5 V,	V <sub>O</sub> = 2.1 V			100	μΑ
los§	A port	V <sub>CC</sub> = 5.5 V,	$V_{O} = 0$	-30		-150	mA
	A port to B port					100	
ICC	B port to A port	V <sub>CC</sub> = 5.5 V,	IO = 0			120	mA
0	AI port				5.5		
Ci	Control inputs	V <sub>I</sub> = 0.5 V or 2.5 V			5.5		pF
Co	AO ports	$V_{O} = 0.5 V \text{ or } 2.5 V$			5.5		pF
C <sub>io</sub>	B port per IEEE Std 1194.1-1991	V <sub>CC</sub> = 0 to 5.5 V				5.5	pF

<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

<sup>‡</sup> For I/O ports, the parameters I<sub>IH</sub> and I<sub>IL</sub> include the off-state output current. § Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

#### live-insertion specifications over recommended operating free-air temperature range

PAR	PARAMETER TEST CONDITIONS				MIN	MAX	UNIT
		$V_{CC} = 0$ to 4.5 V				450	
ICC (BI	AS V <sub>CC</sub> )	$V_{CC} = 4.5 V \text{ to } 5.5 V$	$V_{B} = 0 \text{ to } 2 \text{ V},$	$V_{I}$ (BIAS $V_{CC}$ ) = 4.5 V to 5.5 V		10	μA
VO	B port	$V_{CC} = 0,$	$V_{I}$ (BIAS $V_{CC}$ ) = 5 V		1.62	2.1	V
		$V_{CC} = 0$ ,	V <sub>B</sub> = 1 V,	$V_I$ (BIAS $V_{CC}$ ) = 4.5 V to 5.5 V	-1		
IO	B port	$V_{CC} = 0$ to 2.2 V,	OEB = 0 to 5 V			100	μA
		$V_{CC} = 0$ to 5.5 V,	OEB = 0 to 0.8 V			1	mA



# SN74FB1651 **17-BIT TTL/BTL UNIVERSAL STORAGE TRANSCEIVER** WITH BUFFERED CLOCK LINE SCBS1770 – OCTOBER 1993 – REVISED MARCH 2004

# timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			V <sub>CC</sub> = T <sub>A</sub> = 2	= 5 V, 25°C	MIN	МАХ	UNIT
			MIN	MAX			
fclock	Clock frequency			150		150	MHz
tw	Pulse duration	CLK or LE	3.3		3.3		ns
+	Satur time	Data before LE	4.8		4.8		-
t <sub>su</sub>	Setup time	Data before CLK↑	4.9		4.6		ns
+.	Hold time	Data after LE	1.8		1.8		ns
th		Data after CLK↑	1.1		1.1		115



# SN74FB1651 **17-BIT TTL/BTL UNIVERSAL STORAGE TRANSCEIVER** WITH BUFFERED CLOCK LINE SCBS1770 – OCTOBER 1993 – REVISED MARCH 2004

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

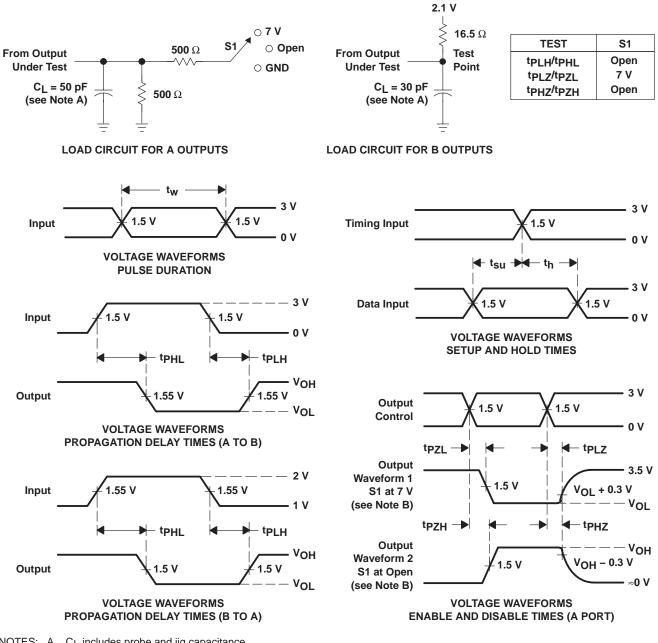
PARAMETER	FROM	TO	V <sub>C</sub>	CC = 5 V A = 25°C	l, C	MIN	MAX	
	(INPUT)	(OUTPUT)	MIN	TYP	MAX			
f <sub>max</sub>			150			150		MH
<sup>t</sup> PLH		_	1.8	3.7	5.3	1.8	6.2	
<sup>t</sup> PHL	AI	B	2.9	4.4	6	2.9	6.6	ns
<sup>t</sup> PLH		B	2.7	4.2	5.8	2.7	6.4	
<sup>t</sup> PHL	LEAB	В	3.5	5	6.5	3.5	7.3	ns
<sup>t</sup> PLH	OL KAD	B	2.3	3.9	5.5	2.3	6	
<sup>t</sup> PHL	CLKAB	В	2.9	4.5	6.1	2.9	6.7	ns
<sup>t</sup> PLH			4.6	6.9	8.8	4.6	9.9	
<sup>t</sup> PHL	2CLKAB	2CLKAB	4.9	6.5	8.1	4.9	8.8	ns
<sup>t</sup> PLH	B		3.5	5.9	7.9	3.5	8	
<sup>t</sup> PHL	В	AO	2.2	3.7	5.3	2.2	5.7	ns
<sup>t</sup> PLH			1.8	3.2	4.6	1.8	5.1	
<sup>t</sup> PHL	LEBA	AO	1.7	3	4.4	1.7	4.7	ns
<sup>t</sup> PLH	01.1/17.4		1.8	3.1	4.6	1.8	5.1	ns
<sup>t</sup> PHL	CLKBA	AO	1.7	3.1	4.6	1.7	4.9	
<sup>t</sup> PLH	2CLKAB	2011/	6.4	9.7	11.8	6.4	13.4	ns
<sup>t</sup> PHL	ZCLKAB	2CLK	4.1	6.9	8.9	4.1	10.3	
<sup>t</sup> PLH	OFR	B	2.7	4.6	6.4	2.7	6.7	
<sup>t</sup> PHL	OEB	В	2.9	4.1	5.9	2.9	6.6	ns
<sup>t</sup> PLH	050	B	2.6	4.3	6.2	2.6	6.6	
<sup>t</sup> PHL	OEB	В	3.4	4.6	6.4	3.4	7	ns
<sup>t</sup> PZH	OEA		1.4	2.9	4.4	1.4	4.9	
<sup>t</sup> PZL	OEA	AO	1.4	2.6	4	1.4	4.6	ns
<sup>t</sup> PHZ	OEA	AO	1.7	3.4	5.1	1.7	5.8	
<sup>t</sup> PLZ	OEA	AU	2.2	3.6	5	2.2	5.5	ns
<sup>t</sup> PZH	OEA		1.7	3.3	4.7	1.7	5.5	
<sup>t</sup> PZL	OEA	AO	1.7	3.1	4.4	1.7	5.1	ns
<sup>t</sup> PHZ	OEA	AO	1.5	2.9	4.5	1.5	5.1	ns
<sup>t</sup> PLZ	UEA	A0	2	3.1	4.6	2	4.8	
<sup>t</sup> sk(p) <sup>†</sup>	Pulse skew, AI to B or B to	AO		1				ns
<sup>t</sup> sk(o) <sup>†</sup>	Output skew, AI to $\overline{B}$ or $\overline{B}$ to	AO		0.5				ns
tt	B outputs (1.3 V to 1.8 V)		0.9	1.7		0.5	4.6	
Transition time	AO outputs (10% to 90%)	0.5	2		0.4	4.2	ns	
ort input pulse rejection	on		1			1		ns

<sup>†</sup> Skew values are applicable for through mode only.



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#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. Cl includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control. C. All input pulses are supplied by generators having the following characteristics: TTL inputs: PRR  $\leq$  10 MHz, Z<sub>Q</sub> = 50  $\Omega$ , t<sub>r</sub>  $\leq$  2.5 ns,
  - tf  $\leq$  2.5 ns; BTL inputs: PRR  $\leq$  10 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>f</sub>  $\leq$  2.5 ns, t<sub>f</sub>  $\leq$  2.5 ns.
- D. The outputs are measured one at a time, with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms



### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74FB1651PCA	ACTIVE	HLQFP	PCA	100	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

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**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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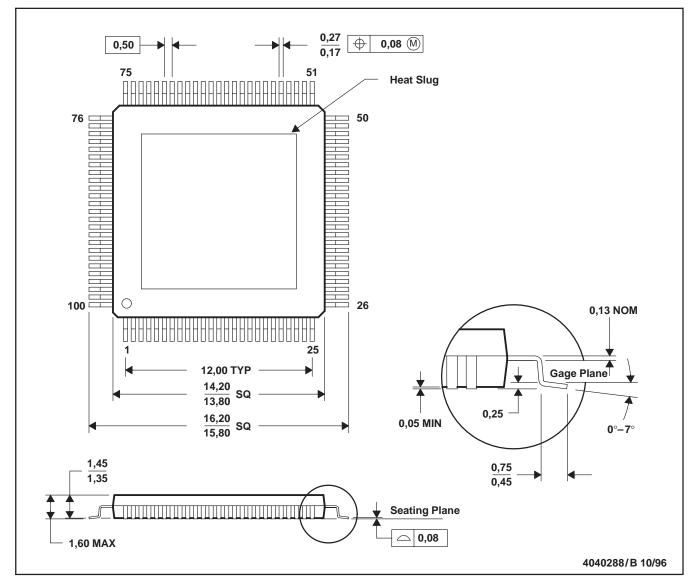
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# **MECHANICAL DATA**

MHTQ003A - JANUARY 1995 - REVISED DECEMBER 1996

#### PCA (S-PQFP-G100)

#### PLASTIC QUAD FLATPACK (DIE DOWN)



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Thermally enhanced molded plastic package with a heat slug (HSL)
- D. Falls within JEDEC MS-026



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